



### Features

- Advanced Trench MOS Technology
- Super Low Gate Charge
- 100% EAS Guaranteed
- Green Device Available

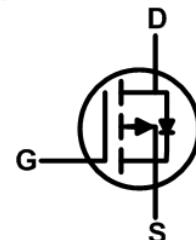
### Product Summary

BVDSS	RDS(ON)	ID
-40V	40mΩ	-27A

### Applications

- Load Switch.
- DC-DC Converter.

### PRPAK5x6 Pin Configuration



### Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
V <sub>DS</sub>	Drain-Source Voltage	-40	V
V <sub>GS</sub>	Gate-Source Voltage	±20	V
I <sub>D</sub> @T <sub>C</sub> =25°C	Continuous Drain Current, -V <sub>GS</sub> @ -10V <sup>1</sup>	-27	A
I <sub>D</sub> @T <sub>C</sub> =100°C	Continuous Drain Current, -V <sub>GS</sub> @ -10V <sup>1</sup>	-17	A
I <sub>D</sub> @T <sub>A</sub> =25°C	Continuous Drain Current, -V <sub>GS</sub> @ -10V <sup>1</sup>	-5.9	A
I <sub>D</sub> @T <sub>A</sub> =70°C	Continuous Drain Current, -V <sub>GS</sub> @ -10V <sup>1</sup>	-4.7	A
I <sub>DM</sub>	Pulsed Drain Current <sup>2</sup>	-54	A
EAS	Single Pulse Avalanche Energy <sup>3</sup>	42	mJ
I <sub>AS</sub>	Avalanche Current	-29	A
P <sub>D</sub> @T <sub>C</sub> =25°C	Total Power Dissipation <sup>4</sup>	41.7	W
T <sub>STG</sub>	Storage Temperature Range	-55 to 150	°C
T <sub>J</sub>	Operating Junction Temperature Range	-55 to 150	°C

### Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
R <sub>θJA</sub>	Thermal Resistance Junction-Ambient <sup>1</sup>	---	62	°C/W
R <sub>θJC</sub>	Thermal Resistance Junction-Case <sup>1</sup>	---	3	°C/W

P-Channel Electrical Characteristics ( $T_J=25^\circ\text{C}$ , unless otherwise noted)

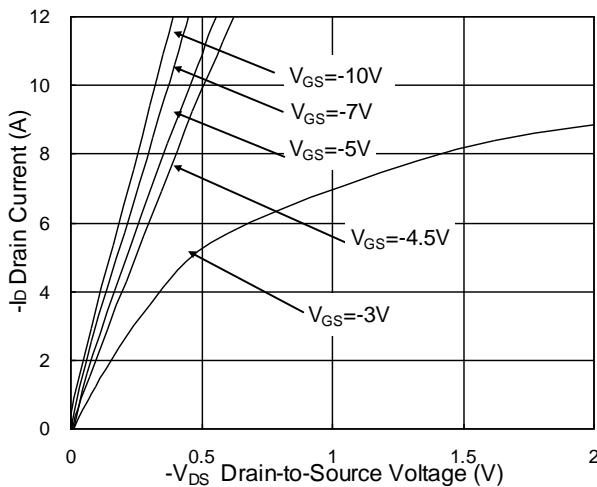
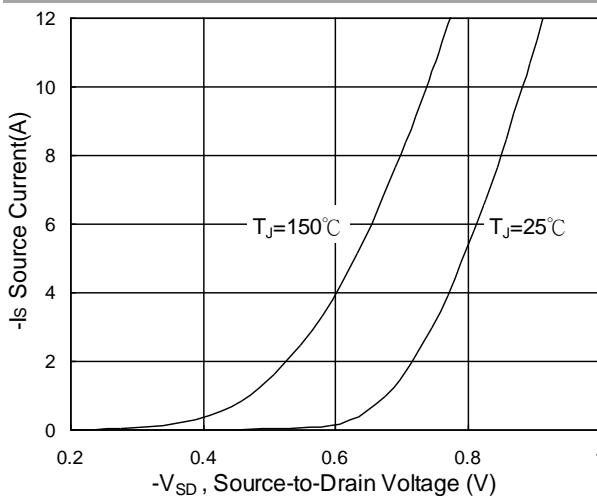
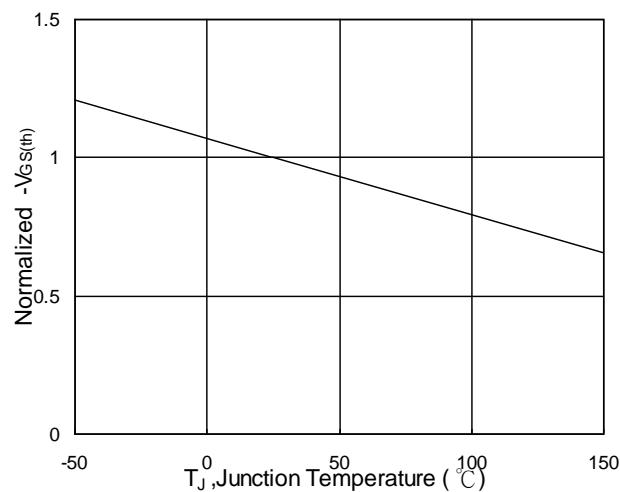
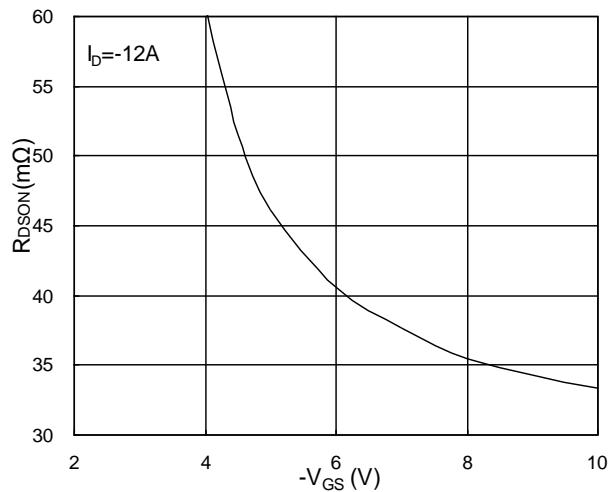
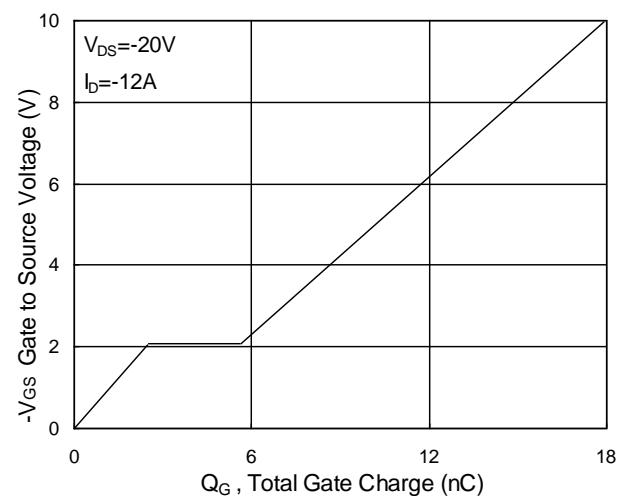
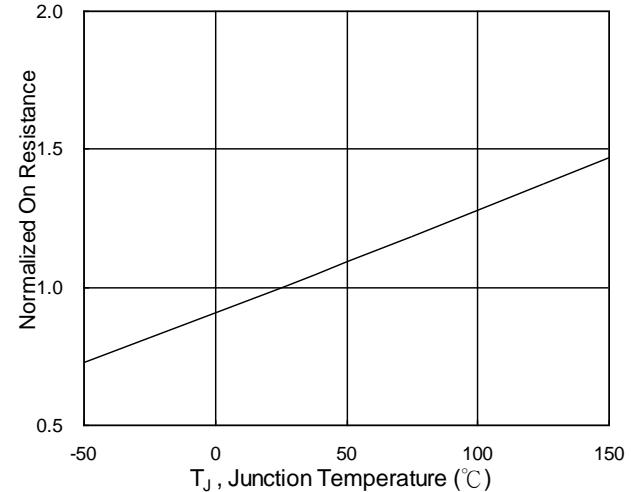
Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$\text{BV}_{\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}$ , $I_D=-250\mu\text{A}$	-40	---	---	V
$\Delta \text{BV}_{\text{DSS}}/\Delta T_J$	$\text{BV}_{\text{DSS}}$ Temperature Coefficient	Reference to $25^\circ\text{C}$ , $I_D=-1\text{mA}$	---	-0.012	---	$\text{V}/^\circ\text{C}$
$R_{\text{DS}(\text{ON})}$	Static Drain-Source On-Resistance <sup>2</sup>	$V_{\text{GS}}=-10\text{V}$ , $I_D=-18\text{A}$	---	---	40	$\text{m}\Omega$
		$V_{\text{GS}}=-4.5\text{V}$ , $I_D=-12\text{A}$	---	---	65	
$V_{\text{GS}(\text{th})}$	Gate Threshold Voltage	$V_{\text{GS}}=V_{\text{DS}}$ , $I_D=-250\mu\text{A}$	-1.0	---	-2.5	V
$\Delta V_{\text{GS}(\text{th})}$	$V_{\text{GS}(\text{th})}$ Temperature Coefficient		---	4.32	---	$\text{mV}/^\circ\text{C}$
$I_{\text{DSS}}$	Drain-Source Leakage Current	$V_{\text{DS}}=-32\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $T_J=25^\circ\text{C}$	---	---	1	$\text{uA}$
		$V_{\text{DS}}=-32\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $T_J=55^\circ\text{C}$	---	---	5	
$I_{\text{GSS}}$	Gate-Source Leakage Current	$V_{\text{GS}}=\pm 20\text{V}$ , $V_{\text{DS}}=0\text{V}$	---	---	$\pm 100$	nA
$g_{\text{fs}}$	Forward Transconductance	$V_{\text{DS}}=-5\text{V}$ , $I_D=-18\text{A}$	---	12.6	---	S
$R_g$	Gate Resistance	$V_{\text{DS}}=0\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $f=1\text{MHz}$	---	13	---	$\Omega$
$Q_g$	Total Gate Charge (-4.5V)	$V_{\text{DS}}=-20\text{V}$ , $V_{\text{GS}}=-4.5\text{V}$ , $I_D=-12\text{A}$	---	9	---	$\text{nC}$
$Q_{\text{gs}}$	Gate-Source Charge		---	2.54	---	
$Q_{\text{gd}}$	Gate-Drain Charge		---	3.1	---	
$T_{\text{d}(\text{on})}$	Turn-On Delay Time	$V_{\text{DD}}=-15\text{V}$ , $V_{\text{GS}}=-10\text{V}$ , $R_G=3.3\Omega$ , $I_D=-1\text{A}$	---	19.2	---	$\text{ns}$
$T_r$	Rise Time		---	12.8	---	
$T_{\text{d}(\text{off})}$	Turn-Off Delay Time		---	48.6	---	
$T_f$	Fall Time		---	4.6	---	
$C_{\text{iss}}$	Input Capacitance	$V_{\text{DS}}=-15\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $f=1\text{MHz}$	---	1004	---	$\text{pF}$
$C_{\text{oss}}$	Output Capacitance		---	108	---	
$C_{\text{rss}}$	Reverse Transfer Capacitance		---	80	---	

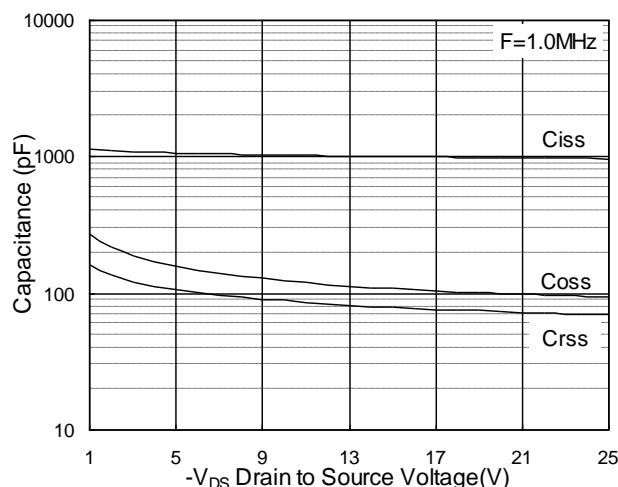
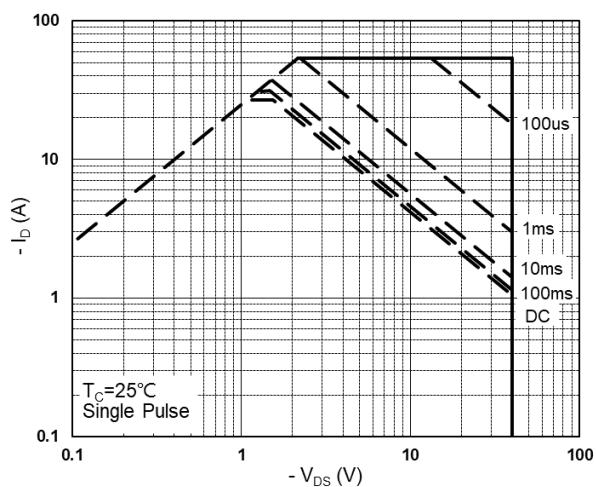
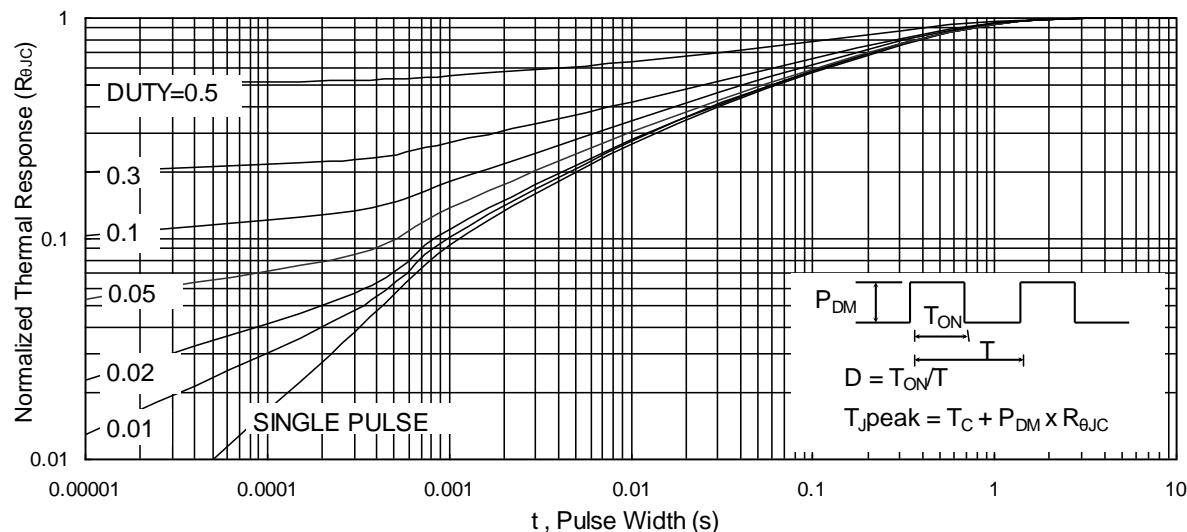
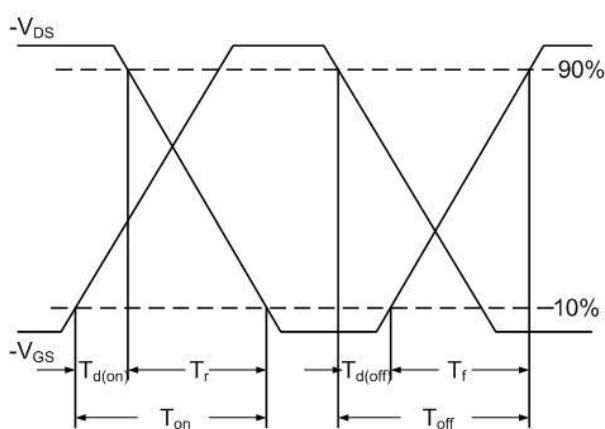
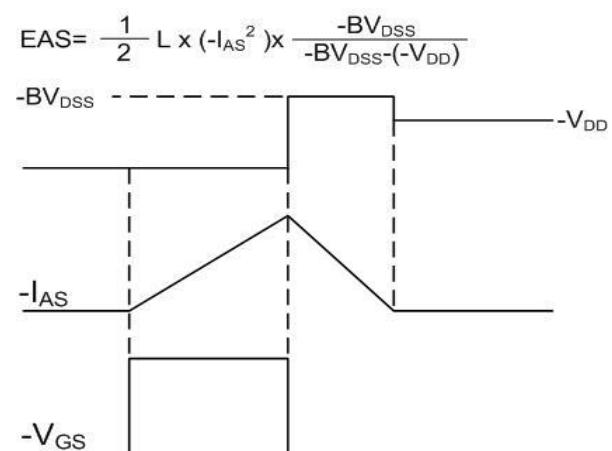
## Diode Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$I_s$	Continuous Source Current <sup>1,5</sup>	$V_G=V_D=0\text{V}$ , Force Current	---	---	-27	A
$I_{\text{SM}}$	Pulsed Source Current <sup>2,5</sup>		---	---	-54	A
$V_{\text{SD}}$	Diode Forward Voltage <sup>2</sup>	$V_{\text{GS}}=0\text{V}$ , $I_s=-1\text{A}$ , $T_J=25^\circ\text{C}$	---	---	-1	V

Note :

- 1.The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width  $\leq 300\mu\text{s}$  , duty cycle  $\leq 2\%$
- 3.The EAS data shows Max. rating . The test condition is  $V_{\text{DD}}=-25\text{V}$ ,  $V_{\text{GS}}=-10\text{V}$ ,  $L=0.1\text{mH}$ ,  $I_{\text{AS}}=-29\text{A}$
- 4.The power dissipation is limited by  $150^\circ\text{C}$  junction temperature
- 5.The data is theoretically the same as  $I_D$  and  $I_{\text{DM}}$  , in real applications , should be limited by total power dissipation.

**P-Channel Typical Characteristics**

**Fig.1 Typical Output Characteristics**

**Fig.3 Source Drain Forward Characteristics**

**Fig.5 Normalized  $V_{GS(th)}$  vs  $T_J$** 

**Fig.2 On-Resistance vs G-S Voltage**

**Fig.4 Gate-Charge Characteristics**

**Fig.6 Normalized  $R_{DS(on)}$  vs  $T_J$**


**Fig.7 Capacitance**

**Fig.8 Safe Operating Area**

**Fig.9 Normalized Maximum Transient Thermal Impedance**

**Fig.10 Switching Time Waveform**

**Fig.11 Unclamped Inductive Waveform**